

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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## NGTD9R120F2

# **Fast Switching Rectifier Die**

Fast switching low Vf rectifier die for free-wheeling applications.

#### **Features**

- Fast Switching
- Low Vf

## **Typical Applications**

- Industrial Motor Control
- Solar PV Inverters

#### **MAXIMUM RATINGS**

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	$V_{RRM}$	1200	V
Max Forward Conduction Current	IF	(Note 1)	Α
Maximum Junction Temperature	TJ	175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Depending on thermal properties of assembly.

#### **MECHANICAL DATA**

Parameter	Value	Unit	
Die Size	2900 x 2900	μm <sup>2</sup>	
Die Thickness	10	mils	
Wafer Size	150	mm	
Top Pad Size (Anode)	2263 x 2263	μm <sup>2</sup>	
Top Metal (Anode)	4 μm AlSi		
Back Metal (Cathode)	2 μm TiNiAg		
Max possible chips per wafer	1535		
Passivation frontside	Oxide-Nitride		
Reject ink dot size	25 mils		
Recommended storage environment: In original container, in dry nitrogen, or temperature of 18–28°C, 30–65%RH	Type: Bare Wafer in Jar Storage time: < 36 months	Type: Die on tape in ring-pack Storage time: < 3 months	

#### **ORDERING INFORMATION**

Device	Inking?	Shipping	
NGTD9R120F2WP	Yes	Bare Wafer in Jar	
NGTD9R120F2SWK	Yes	Sawn Wafer on Tape	



## ON Semiconductor®

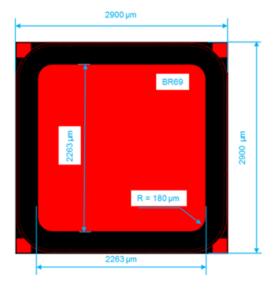
www.onsemi.com

 $V_{RRM}$  = 1200 V  $I_F$  = Limited by  $T_{J(max)}$ 

#### **DIODE DIE**



#### **DIE OUTLINE**



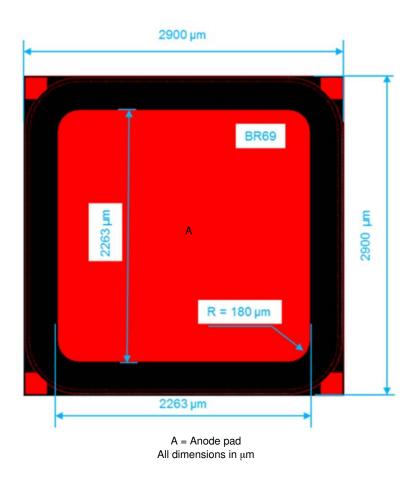
## NGTD9R120F2

## **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ , unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Units	
STATIC CHARACTERISTICS							
Forward Voltage	I <sub>F</sub> = 15 A, T <sub>J</sub> = 25°C	$V_{F}$		2.0	2.6	V	
Reverse Voltage	I <sub>R</sub> = 250 μA, T <sub>J</sub> = 25°C	V <sub>R</sub>	1200			V	
Reverse Current	V <sub>R</sub> = 1200 V, T <sub>J</sub> = 25°C	I <sub>R</sub>	-1.0		1.0	μΑ	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## **DIE LAYOUT**



#### NGTD9R120F2

#### **Further Electrical Characteristic**

Switching characteristics and thermal properties are depending strongly on module design and mounting technology and can therefore not be specified for a bare die.

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